



树脂刀片

软质粘合剂对应硬质加工物。

树脂粘合剂使刀片磨损管控成为可能。

树脂刀片是切割硬质、脆性材料的绝佳选择。例如：QFN/MLF，厚陶瓷基板，HTCC 以及玻璃。

刀片厚度: 75 – 2500µm

金刚石颗粒度: 3 – 250µm

可以定制各种刀刃边缘形状



金刚石颗粒度 (µm)	产品	材料	粘合剂种类
35 至 53	陶瓷封装、传感器	氧化铝/氮化铝	C02/C07 C03/C08
53 至 88	QFN (半蚀刻) + 可润湿QFN (全切割)	铜引线框架 + 封装	D02/D07 D11/D84
53 至 88	QFN (全铜)	铜引线框架 + 封装	E01
35 至 53	DFN (0.3 – 0.5mm)	铜引线框架 + 封装	E31/D02 D62
53 至 88	可润湿QFN首次切割	铜引线框架 + 封装	P07
30 至 45	SAW器件, RF封装	高温共烧陶瓷	QKP/C02
30 至 53	电荷耦合器件/滤光片/透镜	玻璃/石英	QKP/E33
45 至 63	光学和电光学元件	蓝宝石	QKP D70/D67
30 至 53	无源和有源设备。通信模块	低温共烧陶瓷	QKP

树脂刀物料号描述

边缘形状	外径 & 内径		颗粒尺寸 ** (µm)	厚度* (mil)
0 = 标准边缘	1 = 2.188" x 40mm	K = 4.45" x 88.82mm	(003) = 3	(0.03) = 3
4 = 刀片内径3.5" (88.9mm)	2 = 4.256" x 88.82mm	J = 57mm x 40mm	(006) = 6	— (010) = 10
	3 = 3.0" x 40mm	M = 50mm x 40mm	(009) = 9	— (811) = 11.8
	4 = 4.5" x 88.82mm	N = 52.5mm x 40mm	(015) = 15	— (512) = 12.5
	5 = 5.0" x 88.82mm	P = 78mm x 40mm	(020) = 20	— (0.20) = 20
	6 = 4.6" x 88.82mm	R = 64mm x 40mm	(025) = 25	↓ (099) = 99
	7 = 4.7" x 88.82mm	S = 66mm x 40mm	(030) = 30	
	8 = 2.25" x 40mm	T = 74mm x 40mm	(035) = 35	
	9 = 2.5" x 40mm	U = 76.4mm x 40mm	(045) = 45	
	A = 53mm x 40mm	Q = 4.8" x 88.82mm	(053) = 53	
	B = 51mm x 40mm	W = 72mm x 40mm	(063) = 63	
	C = 56mm x 40mm	L = 80mm x 40mm	(075) = 75	
	D = 52mm x 40mm	V = 55mm x 40mm	(088) = 88	
	E = 54mm x 40mm	X = 59mm x 40mm	(105) = 105	
	F = 60mm x 40mm	Y = 77mm x 40mm	(125) = 125	
	G = 4.4" x 88.82mm	Z = 75mm x 40mm	(150) = 150	
	H = 58mm x 40mm		(200) = 200	
示例型号	X 0 777 - 4 006 - 010 - XXX			产品系列
标准边缘	4.5" 外径 x 88.82 mm 内径		6 µm 颗粒	10 mil 厚度

* 取决于金刚石颗粒度 ** 取决于刀片厚度和金刚石颗粒度
其他厚度选项、直径、边缘几何形状和金刚石颗粒度可根据要求提供。